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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/621,110	07/21/2000	Charles Cohn	6-4	4412
75	90 05/08/2002			
Docket Administrator Romm 3C-512 Lucent Technologies Inc 600 Mountain Avenue P O Box 636 Murray Hill, NJ 07974-0636			EXAMINER	
			LUU, CHUONG A	
			ART UNIT	PAPER NUMBER
,,			2825	
			DATE MAILED: 05/08/2002	

Please find below and/or attached an Office communication concerning this application or proceeding.

•			W			
		Application No.	Applicant(s)			
		09/621,110	COHN ET AL.			
	Office Action Summary	Examiner	Art Unit			
		Chuong A Luu	2825			
Period fo	The MAILING DATE of this communication ap	pears on the cover sheet with t	the correspondence address			
	ORTENED STATUTORY PERIOD FOR REPL	Y IS SET TO EXPIRE 03 MO	NTH(S) FROM			
THE - Exte after - If the - If NO - Failu - Any	MAILING DATE OF THIS COMMUNICATION. nsions of time may be available under the provisions of 37 CFR 1. SIX (6) MONTHS from the mailing date of this communication. e period for reply specified above is less than thirty (30) days, a reply period for reply is specified above, the maximum statutory period tire to reply within the set or extended period for reply will, by statut reply received by the Office later than three months after the mailined patent term adjustment. See 37 CFR 1.704(b).	136(a). In no event, however, may a reply sly within the statutory minimum of thirty (3) will apply and will expire SIX (6) MONTHS e. cause the application to become ABANI	be timely filed  b) days will be considered timely. from the mailing date of this communication.  c) DONED (35 U.S.C. § 133).			
1)⊠	Responsive to communication(s) filed on 27	February 2002 .				
2a)⊠	·	his action is non-final.				
3)[	Since this application is in condition for allow	rance except for formal matter	s, prosecution as to the merits is			
•	closed in accordance with the practice under ion of Claims		11, 453 O.G. 213.			
4)⊠	Claim(s) 1-16 is/are pending in the application					
	4a) Of the above claim(s) is/are withdrawn from consideration.					
	5) Claim(s) <u>13-16</u> is/are allowed.					
6)⊠	6)⊠ Claim(s) <u>1-12</u> is/are rejected.					
7)	Claim(s) is/are objected to.					
	Claim(s) are subject to restriction and/	or election requirement.				
• •	ion Papers  The enceification is objected to by the Examina	er				
9)  The specification is objected to by the Examiner.  10)  The drawing(s) filed on is/are: a)  accepted or b)  objected to by the Examiner.						
10)	Applicant may not request that any objection to the					
11)	The proposed drawing correction filed on					
If approved, corrected drawings are required in reply to this Office action.						
12)	The oath or declaration is objected to by the E					
•	under 35 U.S.C. §§ 119 and 120					
-	Acknowledgment is made of a claim for foreig	n priority under 35 U.S.C. § 1	19(a)-(d) or (f).			
	☐ All b)☐ Some * c)☐ None of:					
·	1. Certified copies of the priority documen	its have been received.				
	2. Certified copies of the priority documents have been received in Application No					
* :	Copies of the certified copies of the price application from the International B See the attached detailed Office action for a lis	ureau (PCT Rule 17.2(a)).				
	Acknowledgment is made of a claim for domes					
á	a)  The translation of the foreign language processes the comment of the foreign language processes the comment is made of a claim for domestic the comment is made of a claim for domestic the comment in the comment of the comment o	rovisional application has bee	n received.			
Attachme			•			
1) Noti 2) Noti	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Info	nmary (PTO-413) Paper No(s) rmal Patent Application (PTO-152)			

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#### **DETAILED ACTION**

### **PRIOR ART REJECTIONS**

### **Statutory Basis**

# Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) do not apply to the examination of this application as the application being examined was not (1) filed on or after November 29, 2000, or (2) voluntarily published under 35 U.S.C. 122(b). Therefore, this application is examined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

## Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.

### The Rejections

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Claims 1, 6-8 are rejected under 35 U.S.C. 102(e) as being anticipated by Yamasaki et al. (U.S. 6,077,728)

Yamasaki discloses a method of producing a ceramic package main body by

(1); (7) (a) forming a substrate (1) having a first dielectric layer (2), a conductive layer (3) having a first region insulated from a second region and located above the first dielectric layer (2), and a second dielectric layer (1a) above the conductive layer (3), the second dielectric layer (1a) having a cavity wherein the first and second regions are exposed with the cavity; (b) interconnecting (12)a first lead of an integrated circuit to the first exposed region and interconnecting a second lead of the integrated circuit to the exposed second region (see Figures 1, 7);

- (6) further comprising forming multiple interconnections between the integrated circuit chip and the conductive layer (see Figure 1);
  - (8) wherein steps (a), (b), and (c) occur prior to step (d) (see Figure 1);

Claim 2 is rejected under 35 U.S.C. 103(a) as being unpatentable over Yamasaki et al. (U.S. 6,077,728) in view of Plepys et al. (U.S. 6,140,707)

Yamasaki teaches the above outlined features except for bond pad. However, Plepys discloses a low-cost integrated circuit package with (2) wherein step (b) comprises: coupling a conductor to a bond pad (36) formed on the integrated circuit (32); connecting the conductor directly to the conductive layer (56). It would have been obvious to one of ordinary skill in the art at the time of the invention was made to

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combine the above teachings to manufacture a semiconductor interconnection to improve its performance.

Claims 3-5 and 9 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamasaki et al. (U.S. 6,077,728) in view of Ma (U.S. 6,022,787)

Yamasaki teaches everything above except for ground and power, and signal line. However, Ma disclose a method of making an integrated circuit with (3) further comprising providing one of a ground plane and a power plane in the exposed portion of the conductive layer; (4) further comprising providing at least one connection for a signal line in the exposed portion of the conductive layer; (5) further comprising providing at least one connection for a signal line in the exposed portion of the conductive layer; (9) further comprising: providing a contact area to a ground plane by exposing the portion of the conductive layer (see columns 4, 9, lines 33-43, lines 15-30, respectively). It would have been obvious to one of ordinary skill in the art at the time of the invention was made to combine the above teachings to manufacture a semiconductor interconnection to improve its performance.

Claims 10-12 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamasaki et al. (U.S. 6,077,728) in view of Caillat et al. (U.S. 5,861,322)

Yamasaki teaches the above outlined features except for forming plated through holes in the substrate. However, Caillat discloses a process for manufacturing an interconnection substrate (see column 2, lines 1-36. Figure 9). It would have been

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obvious to one of ordinary skill in the art at the time of the invention was made to combine the above teachings to manufacture a semiconductor interconnection to improve its performance.

# Allowable Subject Matter

Claims 13-16 are allowed.

The following is a statement of reasons for the indication of allowable subject matter: The prior art does not disclose or suggest inter alia the limitations "forming a second conductive layer above the second dielectric layer and forming a cavity in the first region of the second dielectric layer to expose the first and second regions of the first conductive layer and coupling a first lead of the integrated circuit to the exposed first region and a second lead of the integrated circuit to the exposed second region".

#### Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the

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shortened statutory period will expire on the date the advisory action is mailed, and any

extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of

the advisory action. In no event, however, will the statutory period for reply expire later

than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Chuong A Luu whose telephone number is (703)305-

0129. The examiner can normally be reached on M-F (7:30-4:00).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Matthew Smith can be reached on (703)308-1323. The fax phone numbers

for the organization where this application or proceeding is assigned are (703)308-7722

for regular communications and (703)308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or

proceeding should be directed to the receptionist whose telephone number is (703)308-

0956.

Chuong Anh Luu Assistant Examiner

CAL

April 26, 2002

CARIDAD EVERHART
PRIMARY EXAMINER

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